

Fig. 7

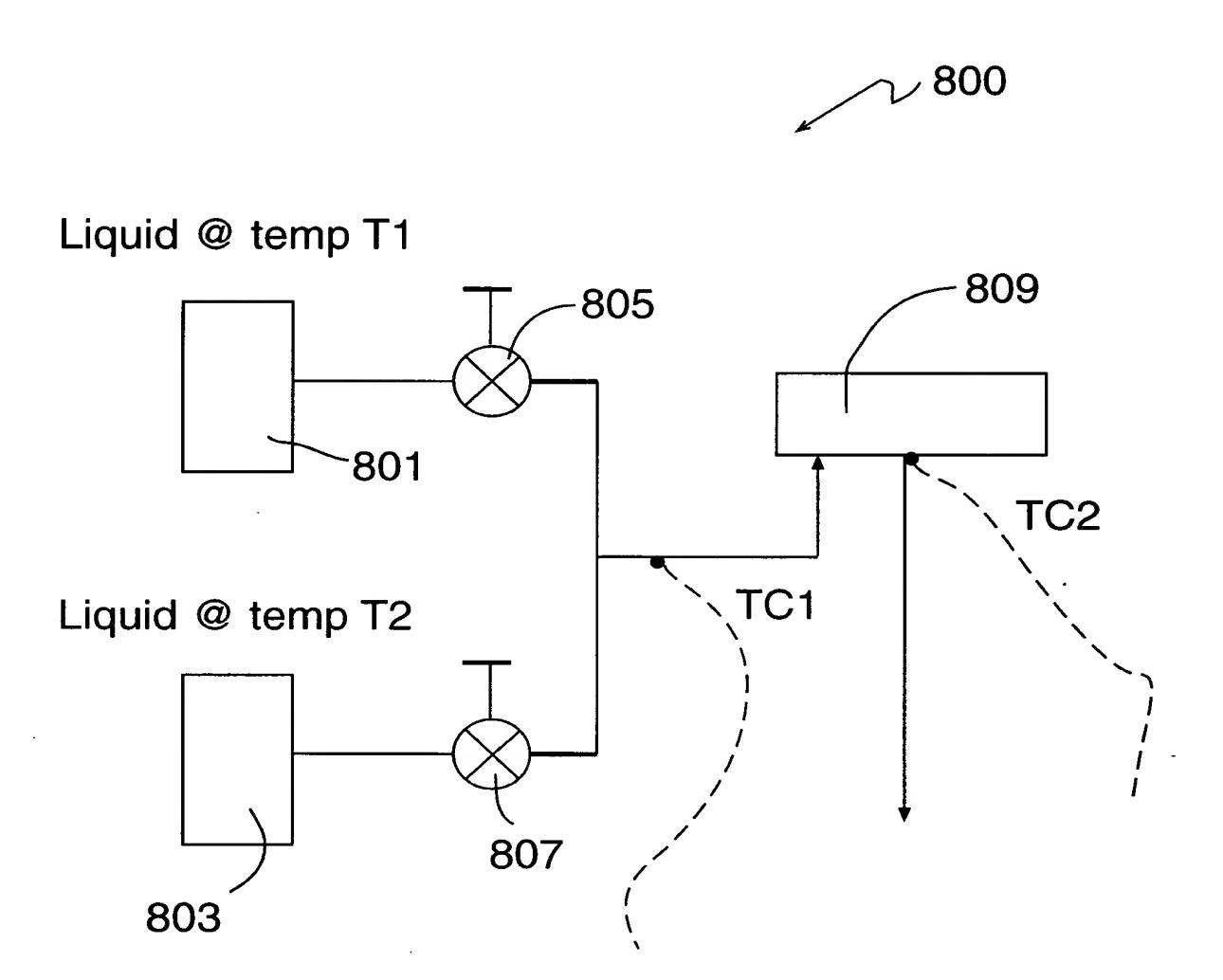
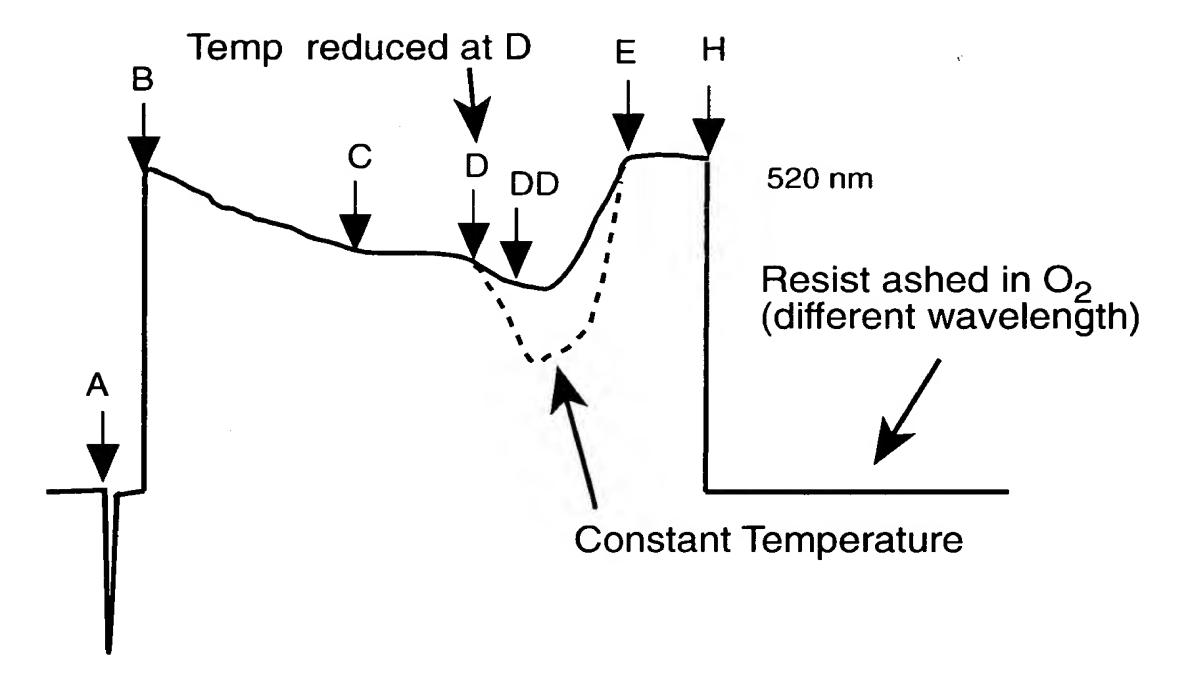
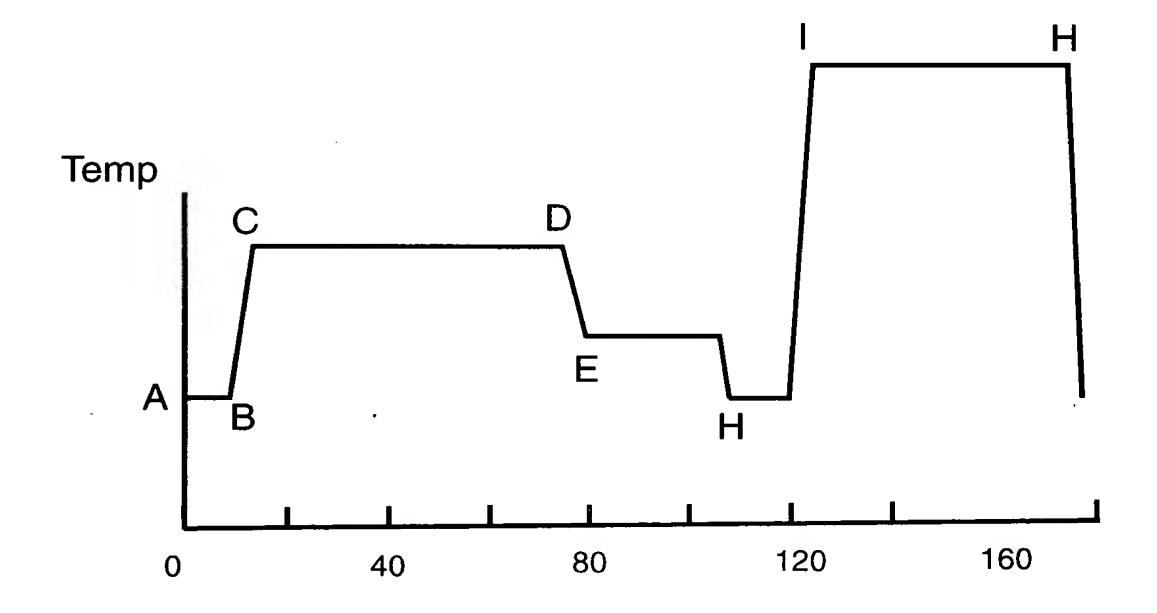


Fig. 8





- A. SF₆ native oxide "breakthrough"
- B. Cl₂ plasma is ignited
- C. WSi_x begins to clear (endpoint)
- D. Polysilicon is exposed
- E. Polysilicon cleared to oxide
- H. Plasma extinguished and O2 feed gas flow is started
- I. O₂ plasma is started
- $J O_2$ plasma is extinguished.

Fig. 10

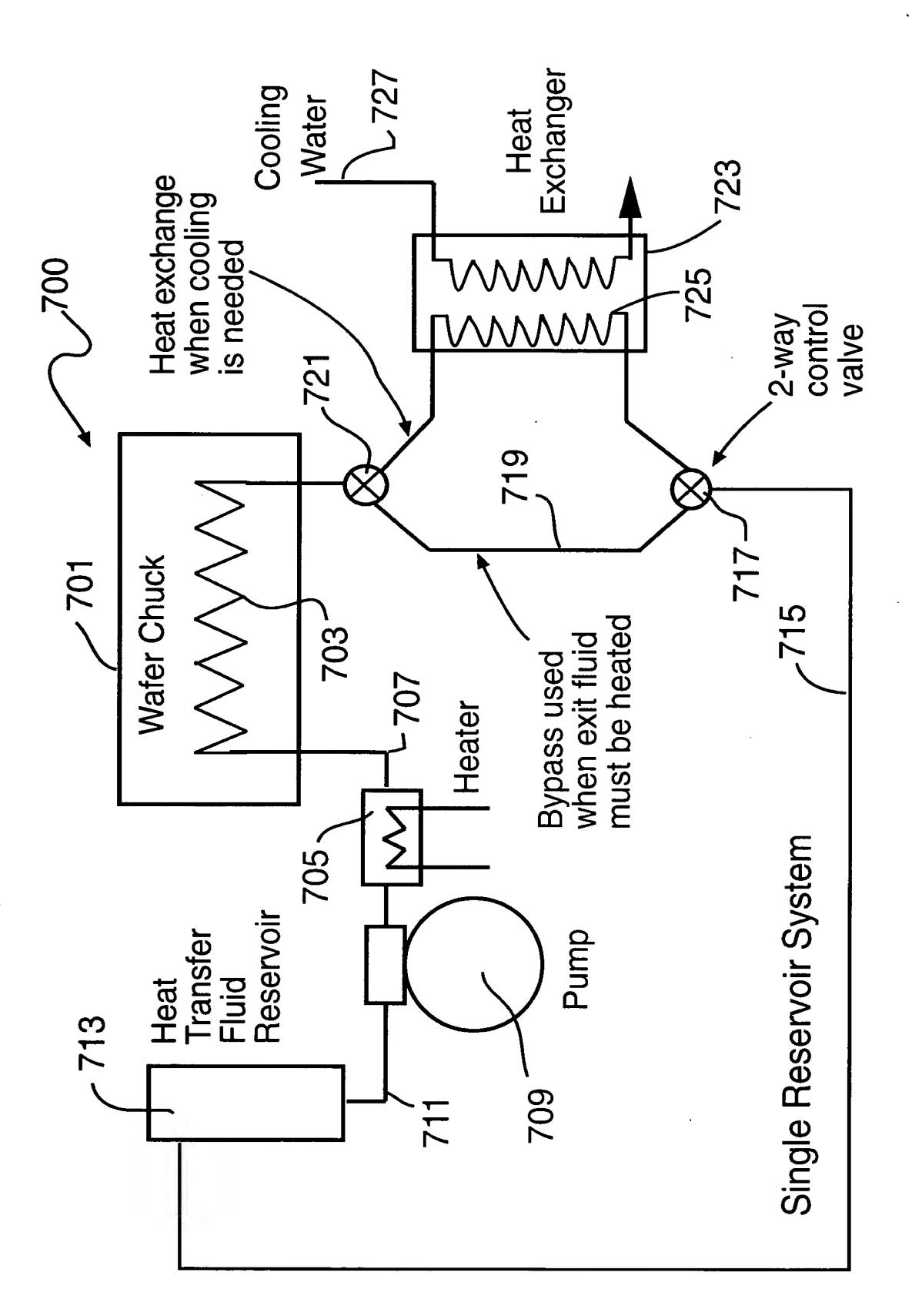


Fig. 7

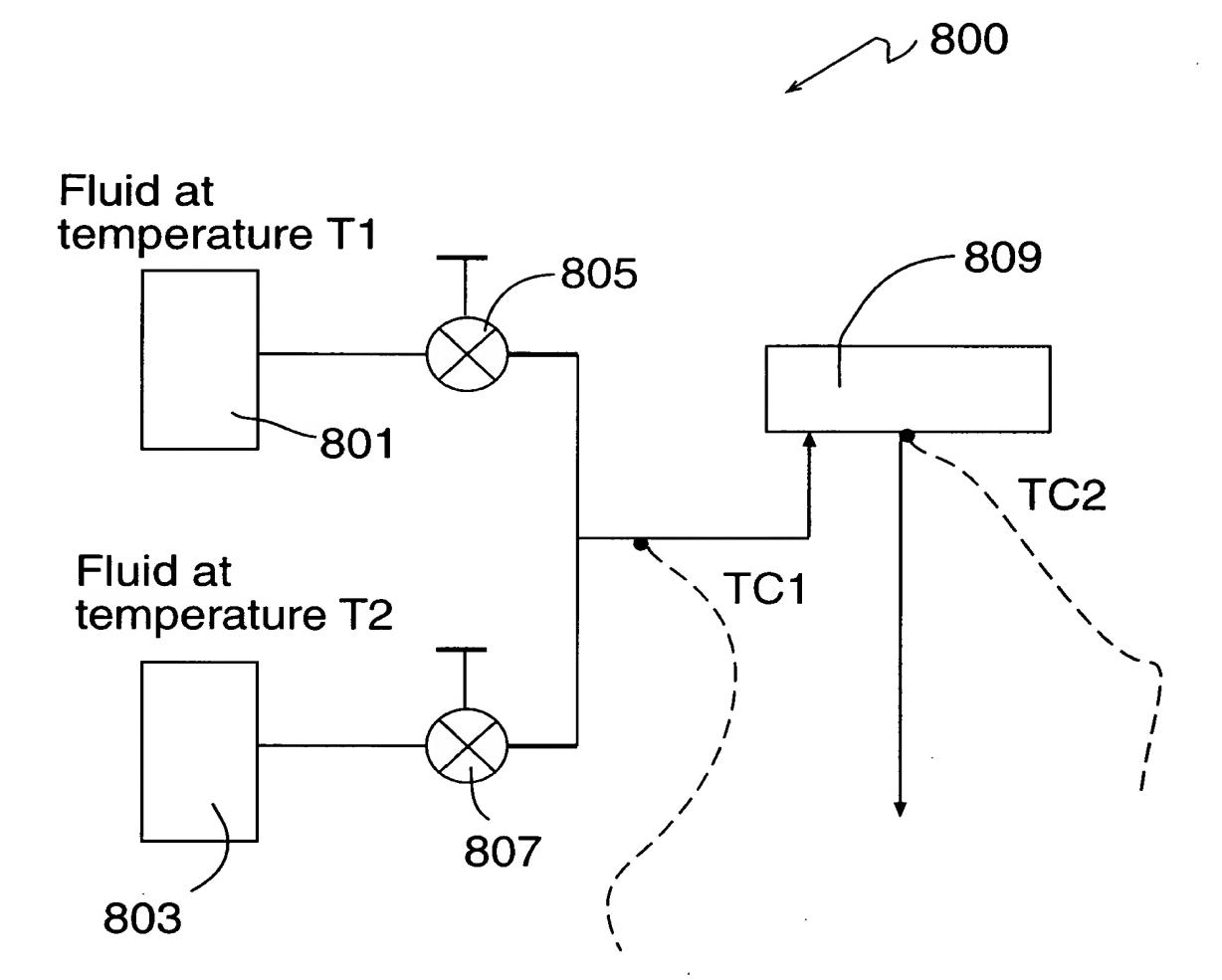
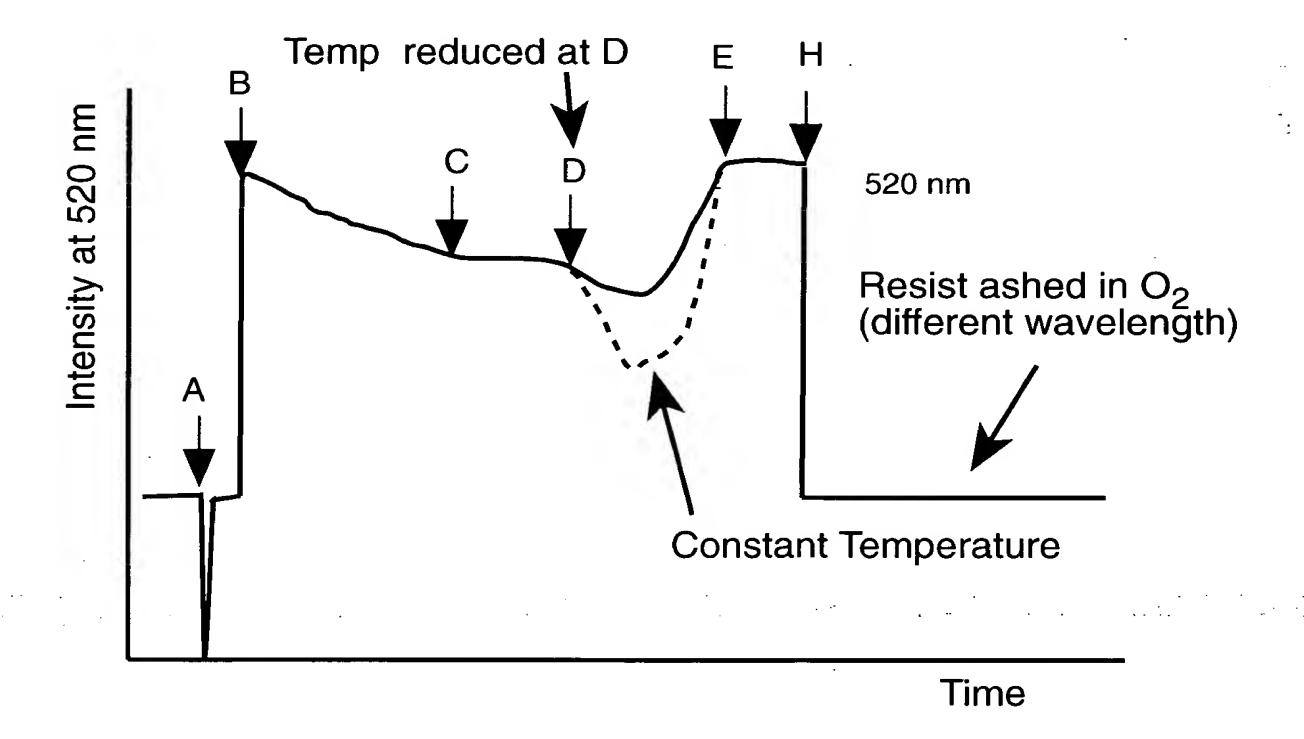
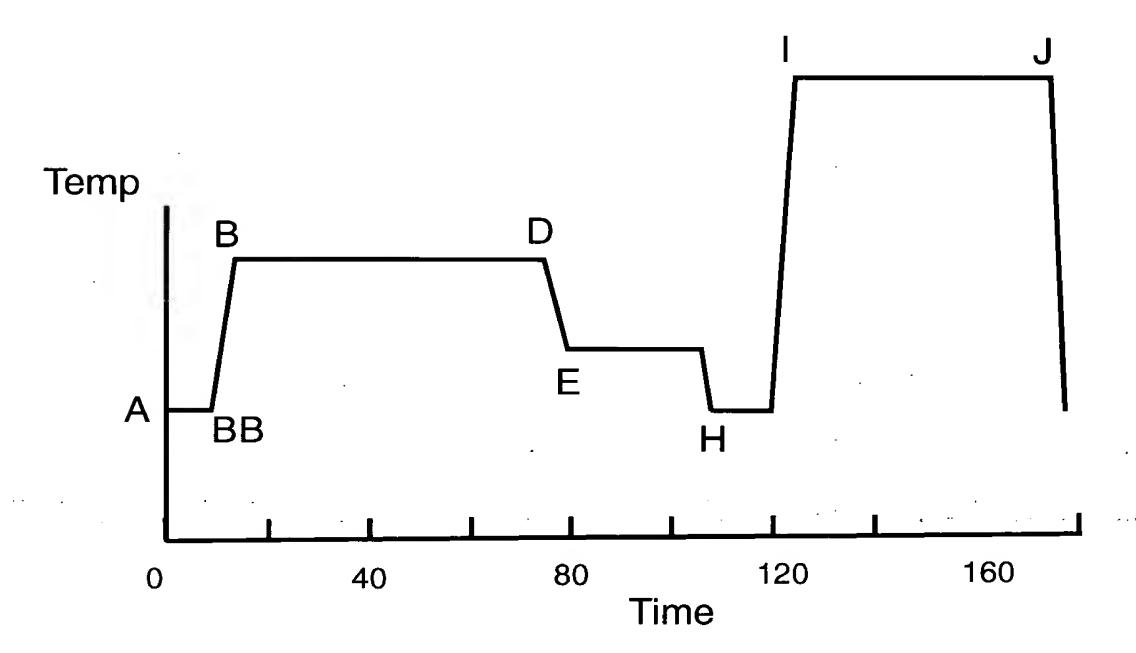


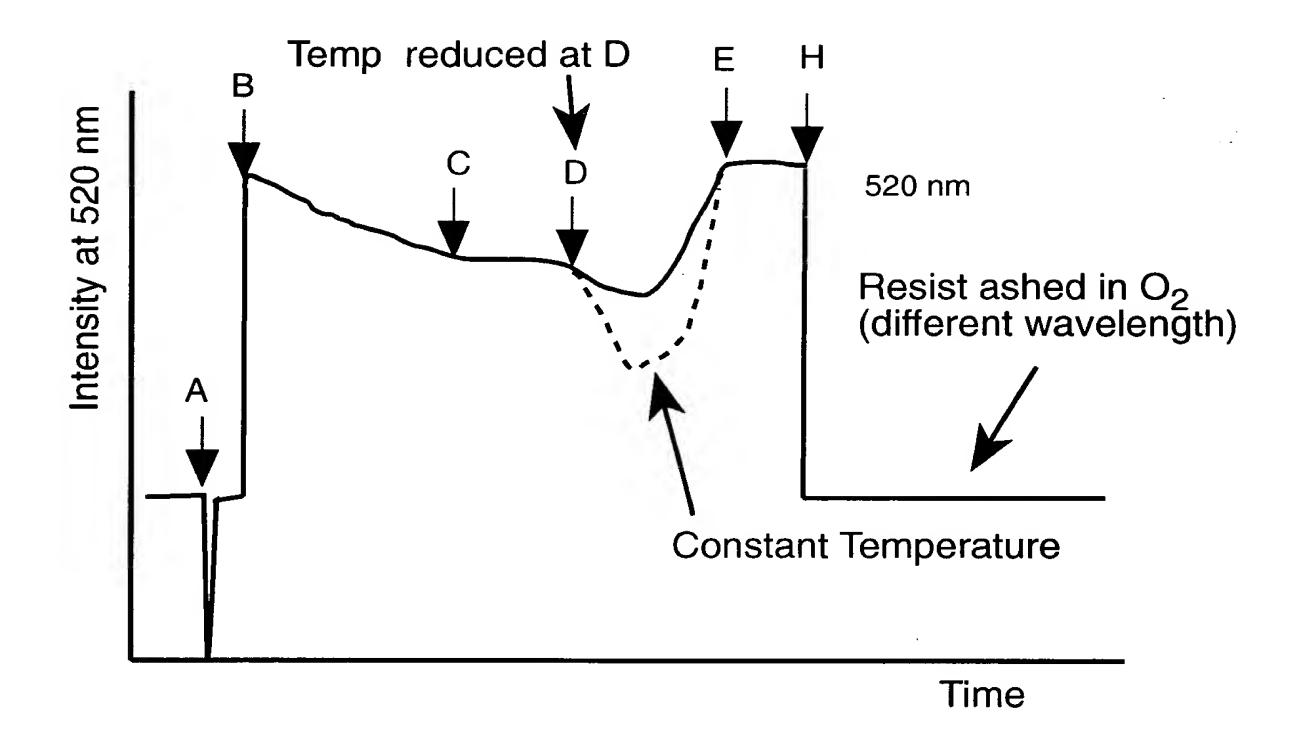
Fig. 8

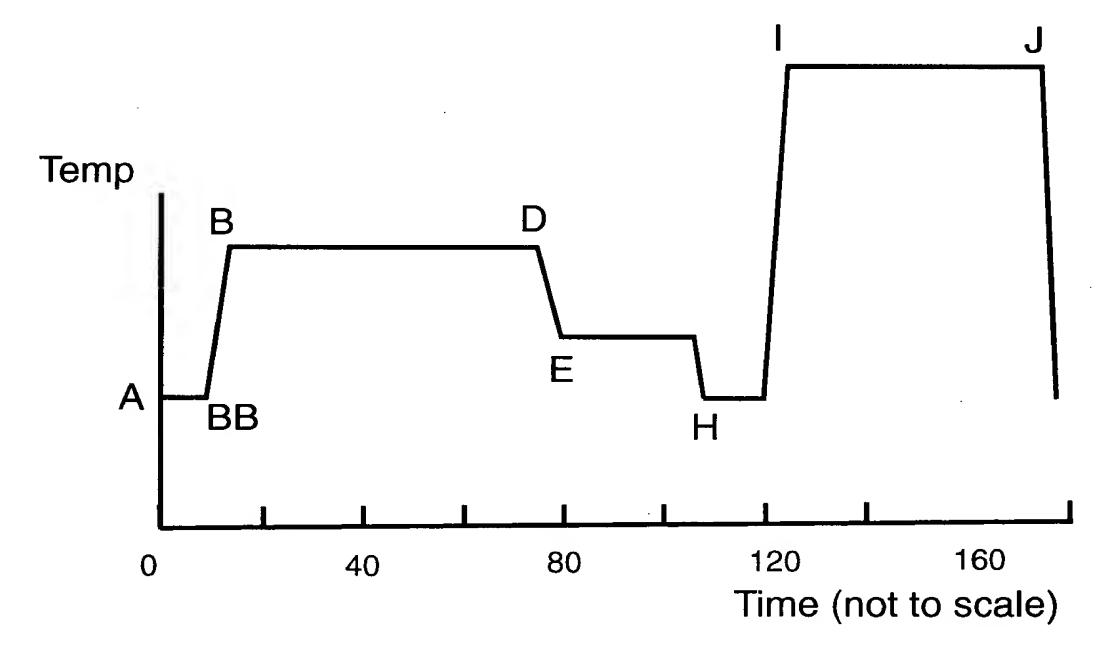




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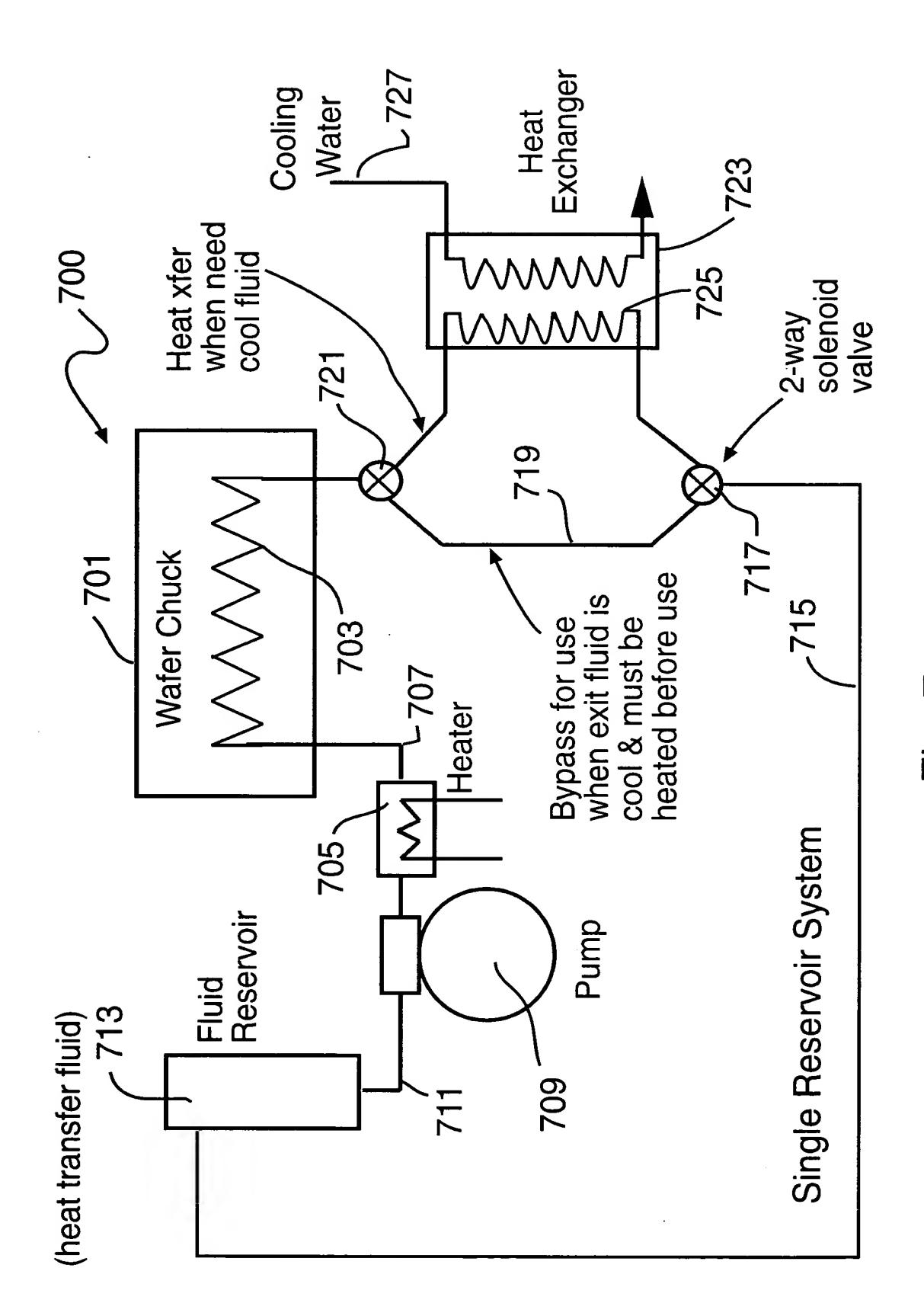


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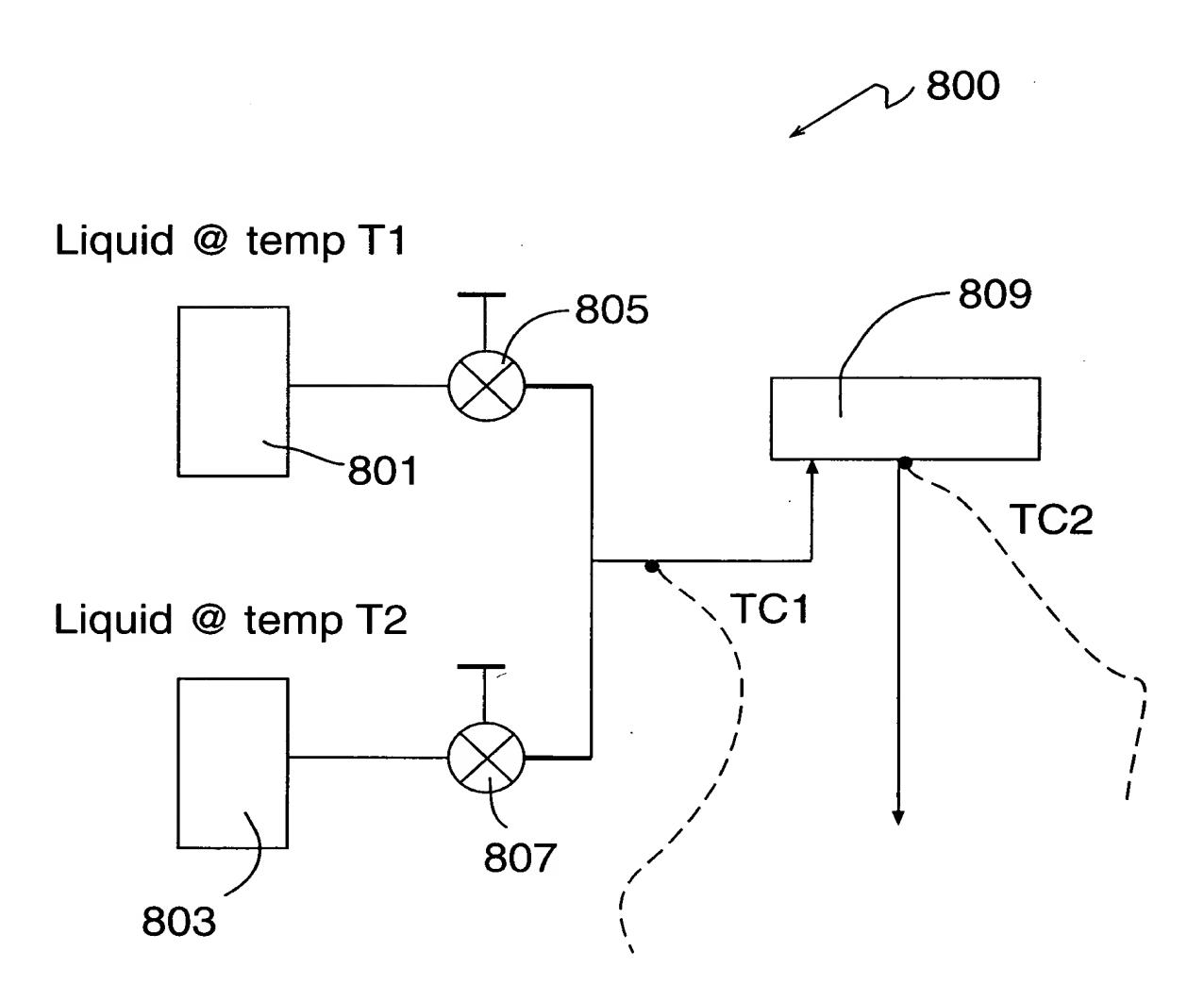
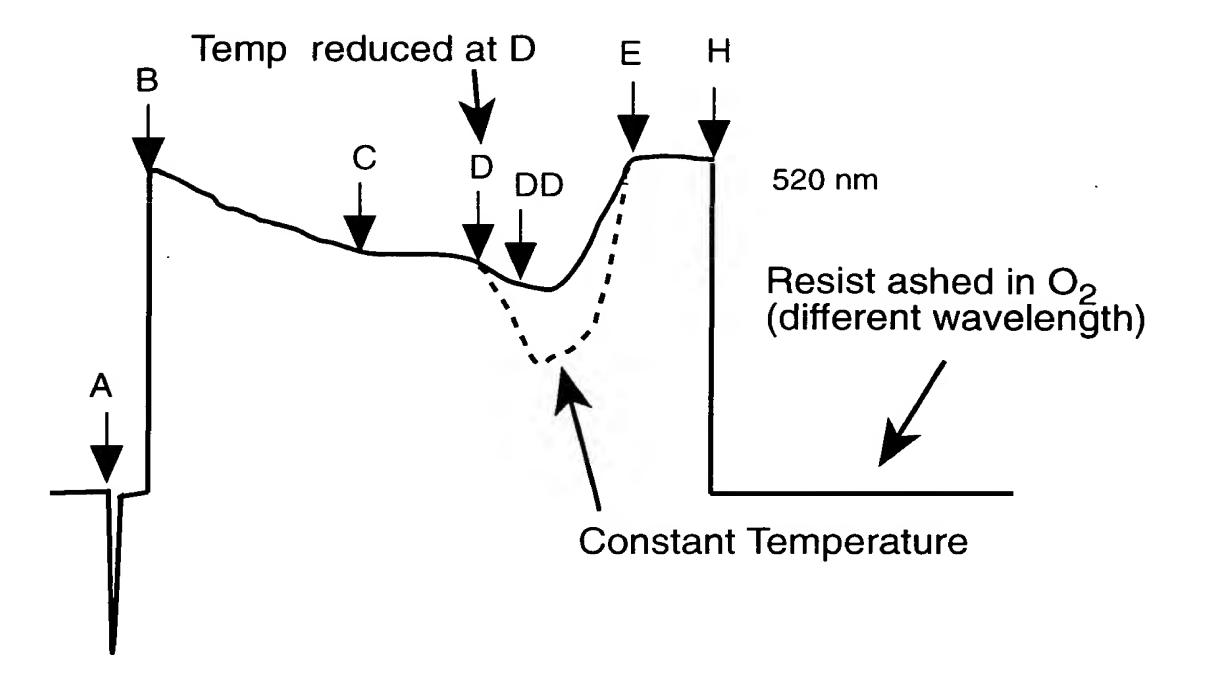
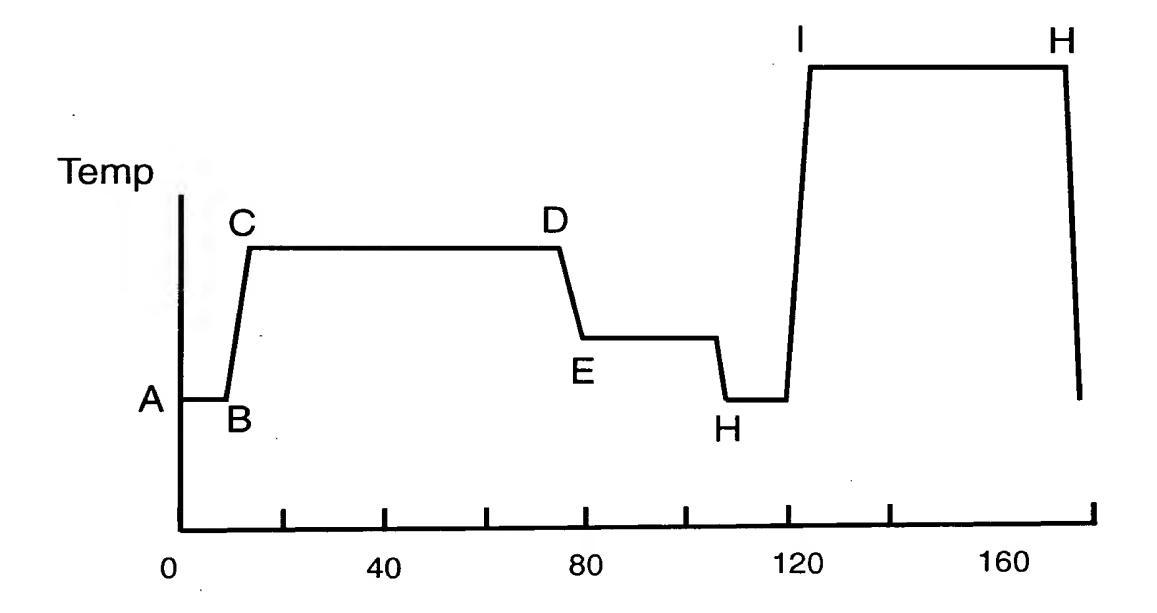


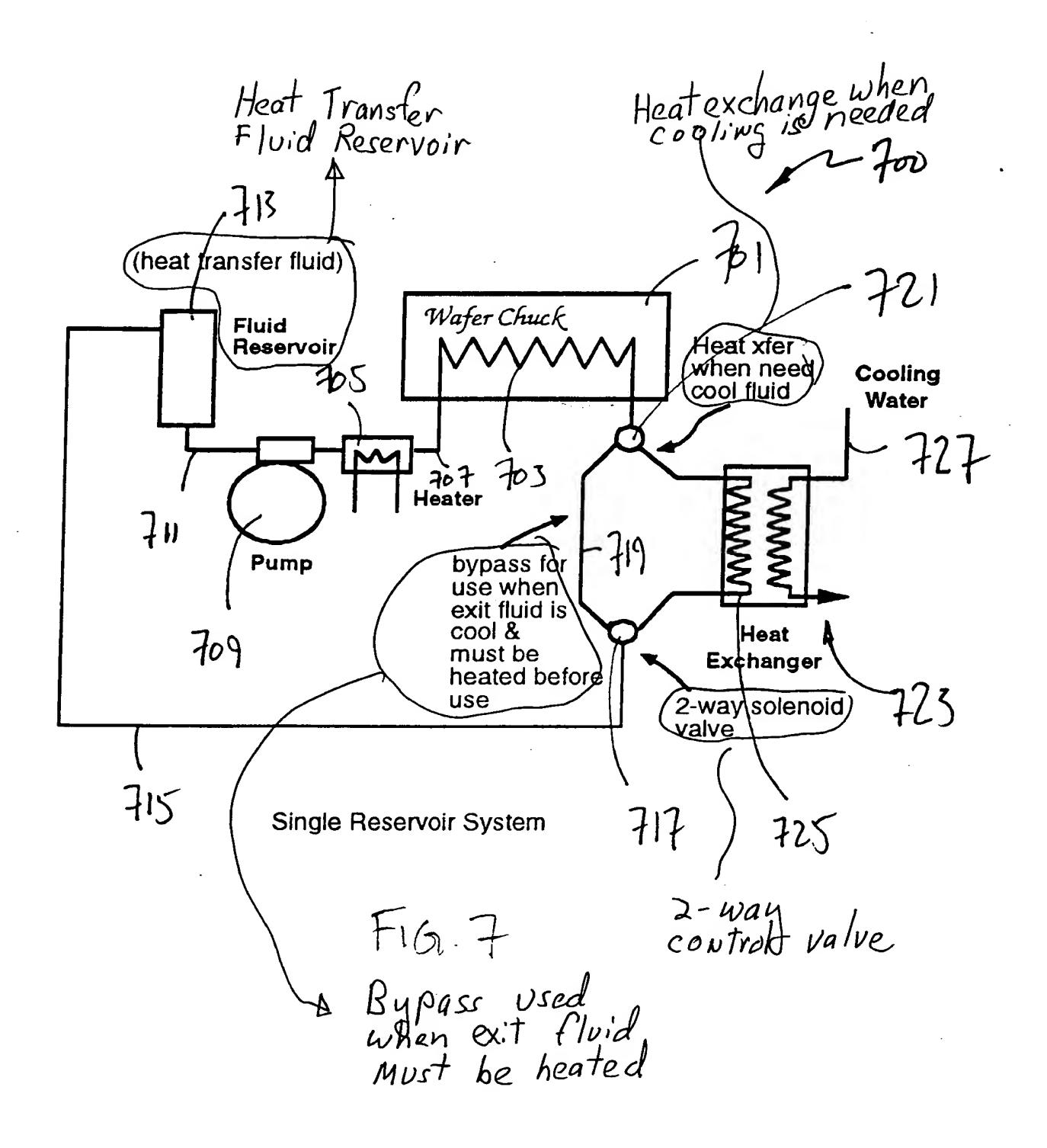
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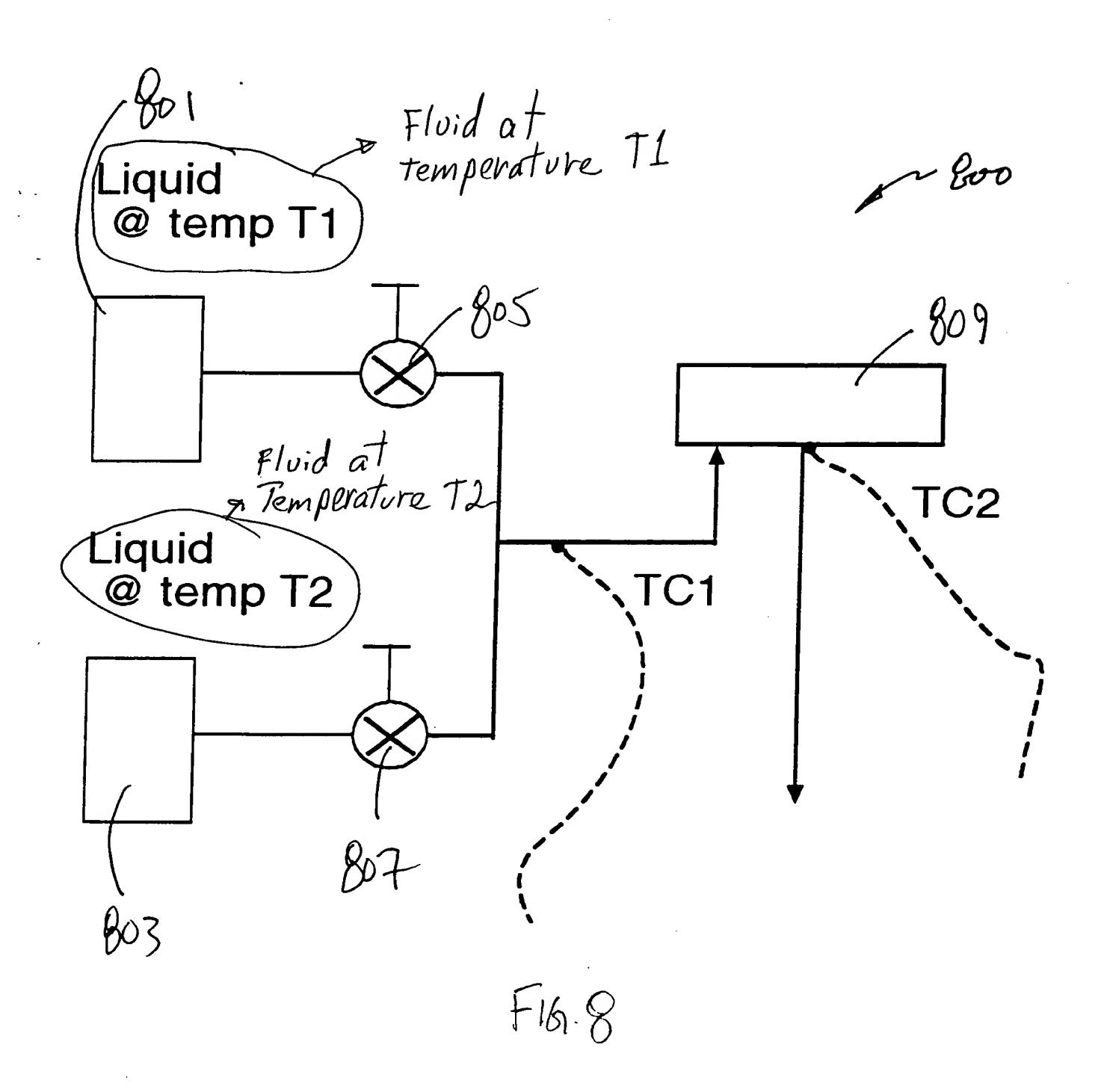


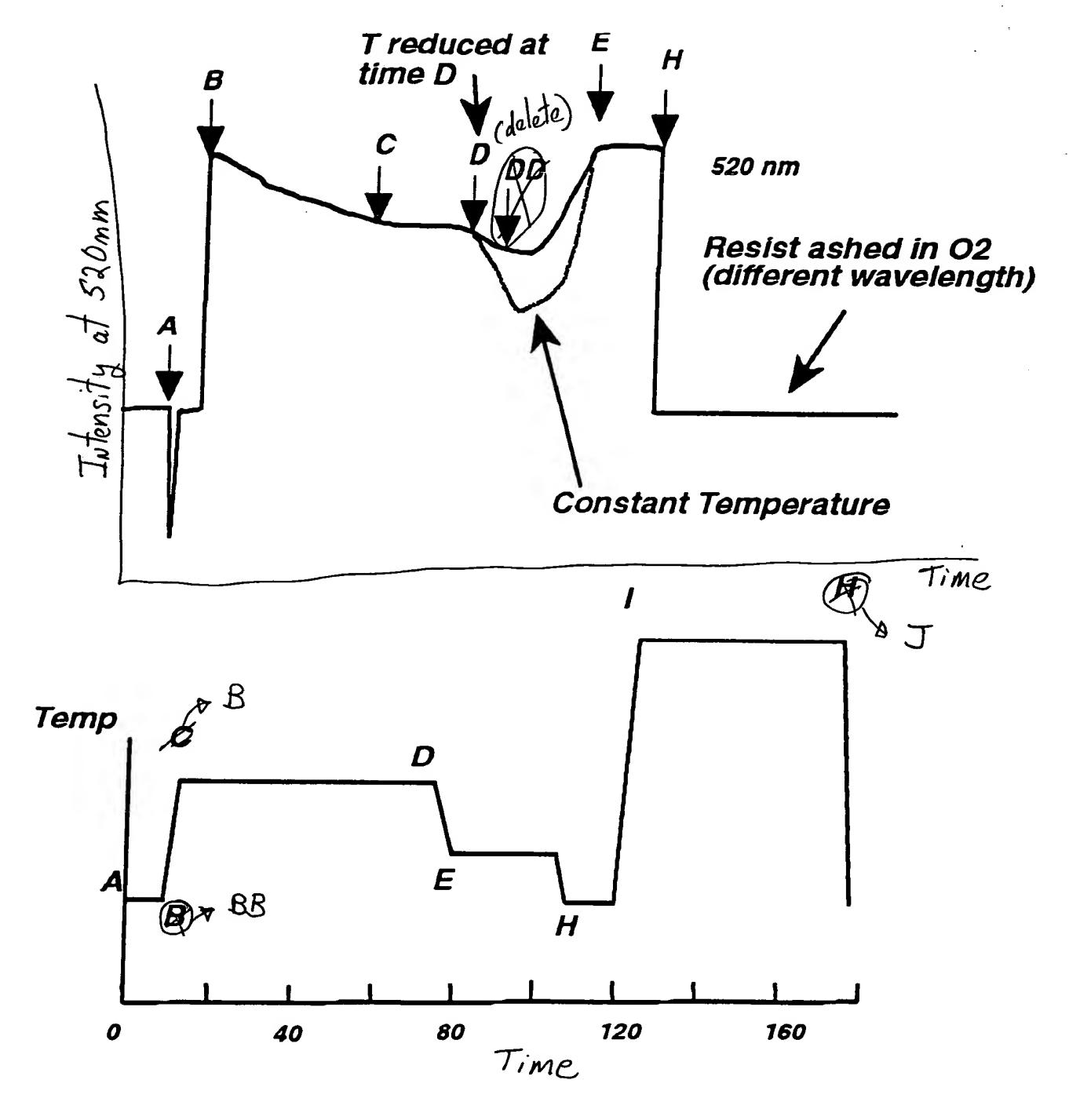


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- B. Cl₂ plasma is ignited
- C. WSix begins to clear (endpoint)
- D. Polysilicon is exposed
- E. Polysilicon cleared to oxide
- H. Plasma extinguished and O2 feed gas flow is started
- I. O2 plasma is started
- J 02 plasma is extinguished.